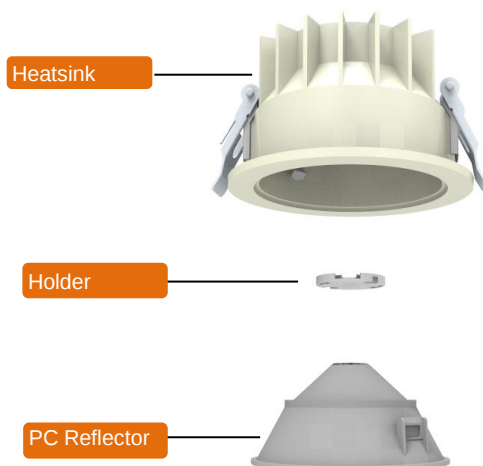


Eden

Eden-5001E Lighting Kits assembly & introduction

Features & Benefits

- * Mechanical compatibility with direct mounting of the COB products to the LED thermal body and thermal performance matching the lumen packages.
- * For Down light designs from 2700 to 3800 lumen.
- * Thermal resistance range R_{th} 0.92°C/W.
- * Full accessory kit with LED cooler Body, PSU mounting shrapnel & lens holder.
- * Other accessories like COB holder & lens separate available.
- * Modular design with mounting holes foreseen for direct mounting of a wide range of LED modules and COB's.
- * Forged from highly conductive aluminum (ADC12).
- * Diameter 160mm - Standard height 85mm, Other heights on request.
- * 3 standard colors - white powder, black powder and gray powder.



- 01) Bridelux: Vero 10/13 Vero SE 10/13 LED engines;
- 02) Cree: XLamp CXA 13xx, XLamp CXB 15xx, CXA 18xx Series engines;
- 03) Citizen: CLU026, CLU027, CLU028, CLU036, CLU038, CLU721, CLU711, CLU701 LED engines;
- 04) Edison: EdiLex III COB LED engines;
- 05) GE lighting: Infusion™ LED engines;
- 06) LG Innotek: 7W, 10W, 16W, 21W, 32W LED engines;
- 07) LumiLEDs: LUXEON 1202/1203/1204/1205/1208 LED engines;
- 08) Lumens: Ergon-COB 15xx, 18xx LED engines;
- 09) Luminus: CXM-6, CHM/CLM/CXM-9/14/18 LED engines;
- 10) Nichia: NVxxx024Z, NVxxx036Z, NFCWxxxB Series LED engines;
- 11) Osram: SOLERIQ® S 9/S13, Z6 Mini LED engines;
- 12) Philips: Fortimo SLM LED engines;
- 13) Prolight Opto: PACJ-7xxx/14xxx/21xxx/28xxx-xxxx, PACK-35xxx/42xxx/57xxx-xxxx engines;
- 14) Samsung: LCxxxC Series, LCxxxD Series LED engines;
- 15) Seoul Semiconductor: SAWxxxxxx Series, DC COB LED engines;
- 16) Tridonic: SLE G5, SLE G6 10/15/17mm LED engines;
- 17) Vossloh-Schwabe: LUGA Shop and LUGA C LED engines;

Order Information

Example: Eden-5001E-WH

- Eden - **1** - **2**
- 1** Product model
- 5001E
- 2** Finish
- WH White
- BK Black
- GY Gray

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.



The product data table

	 <i>Eden</i>
Model No.	Eden-5001E
Heatsink Size	Φ160×85mm
Heatsink Material	ADC12
Heatsink Finish	White/Black/Gray
Weight	622g
Dissipated power (Ths-amb,50°C)	30 (W)
Beam Angle	50°
Thermal Resistance (Rhs-amb)	0.92 (°C/W)

* 3D files are available in ParaSolid, STP and IGS on request

* The thermal resistance R_{th} is determined with a calibrated heat source of 16mm×16mm central placed on the heat sink, T_{amb} 40° and an open environment. Reference data @ heat sink to ambient temperature rise T_{hs-amb} 50°C

The thermal resistance of a LED cooler is not a fix value and will vary with the applied dissipated power P_d

* Dissipated power P_d . Reference data @ heat sink to ambient temperature rise T_{hs-amb} 50°C

The maximal dissipated power needs to be verified in function of required case temperature T_c or junction temperature T_j and related to the estimated ambient temperature where the light fixture will be placed. Please be aware the dissipated power P_d is not the same as the electrical power P_e of a LED module

To calculate the dissipated power please use the following formula: $P_d = P_e \times (1 - \eta_L)$

P_d - Dissipated power

P_e - Electrical power

η_L = Light efficiency of the LED module

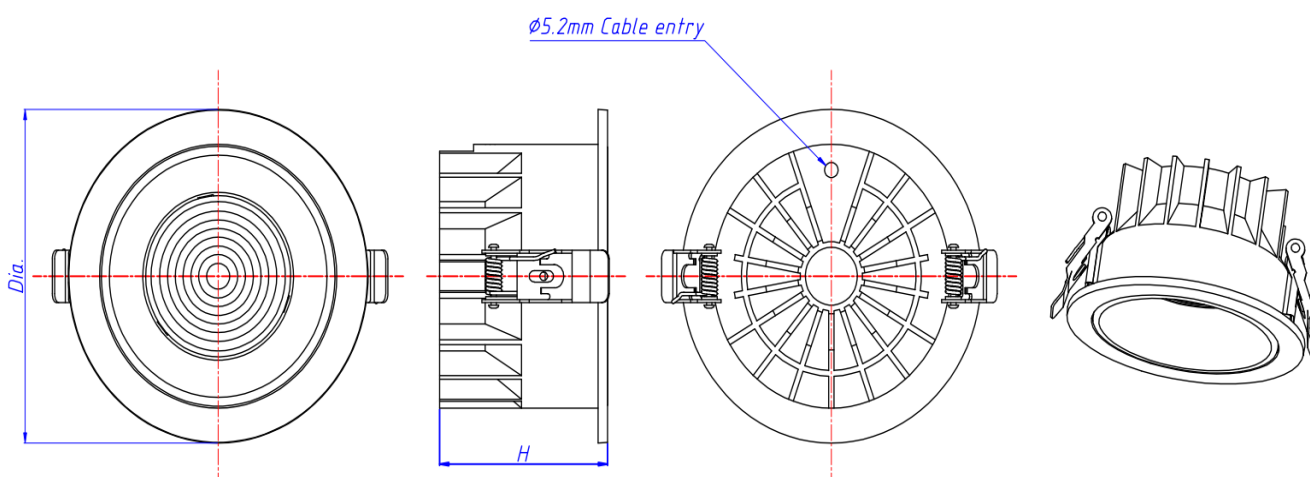


Eden

Eden-5001E Lighting Kits assembly & introduction

Drawings & Type Selection

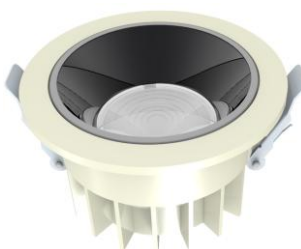
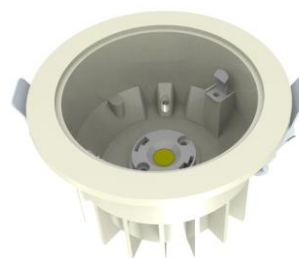
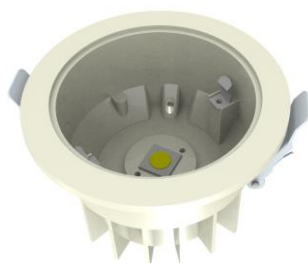
Type	Dia.(mm)	Height(mm)	Power(w)	LES(mm)	Beam Angle	Cut-out(mm)
Eden-5001E	160	85	30	17	50°	145



Components introduction

1. Remove the reflector, Install the COB

2. Fix the COB by the holder and screw



3. Vertically align the shrapnel and press down on the reflector assembly

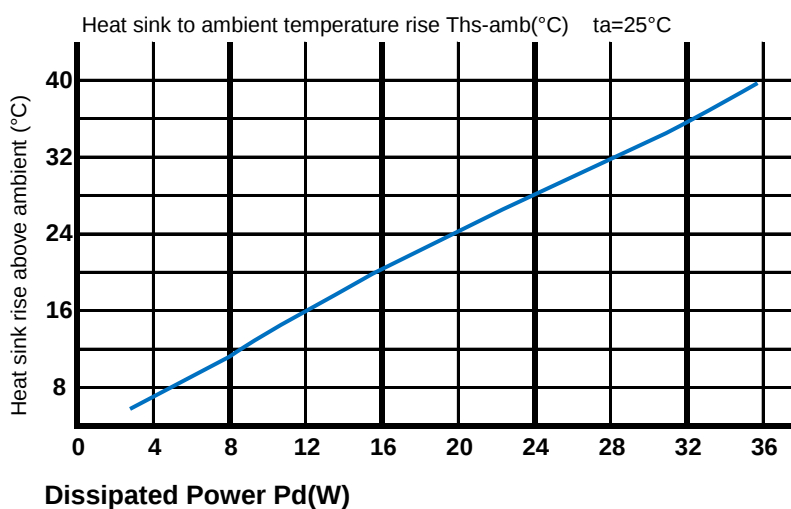


Eden

Eden-5001E Lighting Kits assembly & introduction

The thermal data table

$P_d = P_e \times (1 - \eta_L)$		Heat sink to ambient thermal resistance $R_{hs-amb} (^{\circ}C/W)$	Heat sink to ambient temperature rise $\Delta T_{hs-amb} (^{\circ}C)$
		Eden-5001E	
Dissipated Power $P_d(W)$	5	1.34	7.7
	10	1.10	13
	15	1.07	19
	20	1.02	24.3
	25	0.96	29
	30	0.92	33.5
	35	0.89	38



* Please be aware the dissipated power P_d is not the same as the electrical power P_e of a LED module.

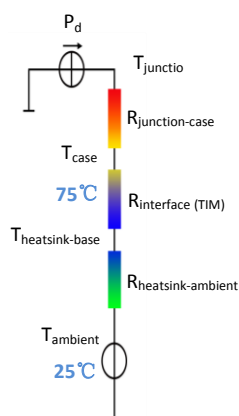
*To calculate the dissipated power please use the following formula: $P_d = P_e \times (1 - \eta_L)$.

P_d - Dissipated power ; P_e - Electrical power ; η_L = Light efficiency of the LED module;

*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (\Delta T_{hs} - T_a) / P_d$

θ - Thermal Resistance [$^{\circ}C/W$]; ΔT_{hs} - Heatsink temperature ; T_a - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface (TIM)}$ [$^{\circ}C/W$], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [$^{\circ}C/W$], and the ambient temperature is $T_{ambient}$ [$^{\circ}C$].

*Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used:

$$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot P_d + T_{ambient}$$